

Using the Transducer-Test-System TTS-030 it will be possible to realise an essential control of all ultrasonic transducers the core part or any wire and ultrasonic die bonder.

Also the way of integration of the transducer into the bond head, as well as the bond tools in the horn will have a decisive influence on the bond behaviour. This can be measured direct in the machine using **TTS-030**.

Furthermore verification of stability of the ultrasonic system over time will be possible. Thus preventive maintenance can be done to prevent bond problems.

In addition tool vibration measurement data from an ODS-20 can be sampled together with the electrical data.

Using the TTS-030 the user can save cost and time and create better bond quality.







Two preconfigured systems are available. One designed for use with fine (thin) wire bond machines. And one for the use with fine (thin) and heavy (thick) wire bond machines as well as with ultrasonic die bond machines. The hardware communicates with the software using serial interface.

TTS Software

Version 3.0 Software release

free configurable views for different measurements Features

free scalable axes of the diagrams

zoom functions

cursor functions for special measurements

save, print and export of data

Microsoft Windows Operating systems

(Windows 2000, Windows XP & Windows 7)

All packages

Resonance frequency Measured values

Resonance impedance Resonance power

vibration excursion

Tool vibration excursion (if ODS connected)

20 to 200 kHz Frequency range

1 Hz Frequency resolution

± 2.5% Full scale accuracy

Voltage constant & power constant Control loop

Short-circuit protected Protection

approx. 10.5" x 6" x 12.4" Dimension

Integrated power supply, 115/230 VAC, 50/60 Hz Power supply

RS232 *) Communication interface

Fine wire package

5 Watts at 22 Ohms Maximum power

Heavy wire / die bonder package

30 Watts at 32 Ohms Maximum power

*) USB to RS232 converters can be used for computers without RS232 connector.